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RQK0204TGDQA

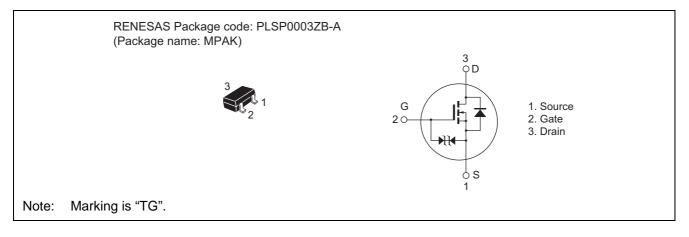
Silicon N Channel MOS FET Power Switching

> REJ03G1324-0300 Rev.3.00 Jun 12, 2006

Features

- Low on-resistance $R_{DS(on)} = 100 \text{ m}\Omega \text{ typ } (V_{GS} = 4.5 \text{ V}, \text{ I}_{D} = 1.2 \text{ A})$
- Low drive current
- High speed switching
- 2.5 V gate drive

Outline



Absolute Maximum Ratings

			$(Ta = 25^{\circ}C)$
Item	Symbol	Ratings	Unit
Drain to source voltage	V _{DSS}	20	V
Gate to source voltage	V _{GSS}	±12	V
Drain current	ID	2.3	А
Drain peak current	I _{D(pulse)} Note1	8.0	А
Body - drain diode reverse drain current	I _{DR}	2.3	А
Channel dissipation	Pch Note2	0.8	W
Channel temperature	Tch	150	°C
Storage temperature	Tstg	-55 to +150	°C

Notes: 1. $PW \le 10 \ \mu s$, duty cycle $\le 1\%$

2. When using the glass epoxy board (FR-4: 40 x 40 x 1 mm)



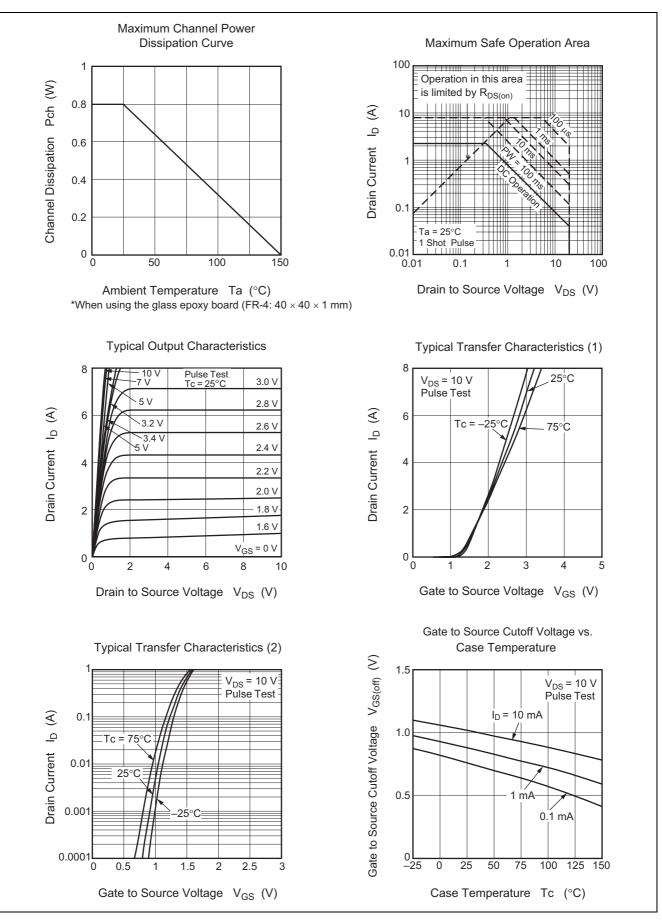
Electrical Characteristics

						$(Ta = 25^{\circ}C)$
Item	Symbol	Min	Тур	Max	Unit	Test conditions
Drain to source breakdown voltage	V _{(BR)DSS}	20	—	—	V	$I_D = 10 \text{ mA}, V_{GS} = 0$
Gate to source breakdown voltage	V _{(BR)GSS}	±12	—	—	V	$I_G = \pm 100 \ \mu A, \ V_{DS} = 0$
Gate to source leak current	I _{GSS}	—	—	±10	μΑ	$V_{GS}=\ \pm 10\ V,\ V_{DS}=0$
Drain to source leak current	I _{DSS}	—	—	1	μA	$V_{DS} = 20 V, V_{GS} = 0$
Gate to source cutoff voltage	V _{GS(off)}	0.4	—	1.4	V	$V_{DS} = 10 \text{ V}, I_D = 1 \text{ mA}$
Drain to source on state resistance	R _{DS(on)}		100	130	mΩ	$I_D = 1.2 \text{ A}, V_{GS} = 4.5 \text{ V}^{\text{Note3}}$
	R _{DS(on)}		146	204	mΩ	$I_D = 1.2 \text{ A}, V_{GS} = 2.5 \text{ V}^{\text{Note3}}$
Forward transfer admittance	y _{fs}	1.5	3.0		S	$I_D = 1.2 \text{ A}, V_{DS} = 10 \text{ V}^{\text{Note3}}$
Input capacitance	Ciss		127	_	pF	V _{DS} = 10 V
Output capacitance	Coss	_	33	—	pF	$V_{GS} = 0$
Reverse transfer capacitance	Crss	_	14	—	pF	f = 1 MHz
Turn - on delay time	t _{d(on)}		11	—	ns	I _D = 1.2 A
Rise time	tr	_	28	—	ns	V _{GS} = 10 V
Turn - off delay time	t _{d(off)}	_	24	—	ns	$R_{L} = 8.3 \Omega$ $Rg = 4.7 \Omega$
Fall time	t _f	_	7	—	ns	
Total gate charge	Qg	_	1.5	—	nC	V _{DD} = 10 V
Gate to source charge	Qgs		0.3	_	nC	$V_{GS} = 5 V$
Gate to drain charge	Qgd		0.4	_	nC	$I_{D} = 2.3 \text{ A}$
Body - drain diode forward voltage	V _{DF}	_	0.85	1.1	V	$I_F = 2.3 \text{ A}, V_{GS} = 0^{Note3}$

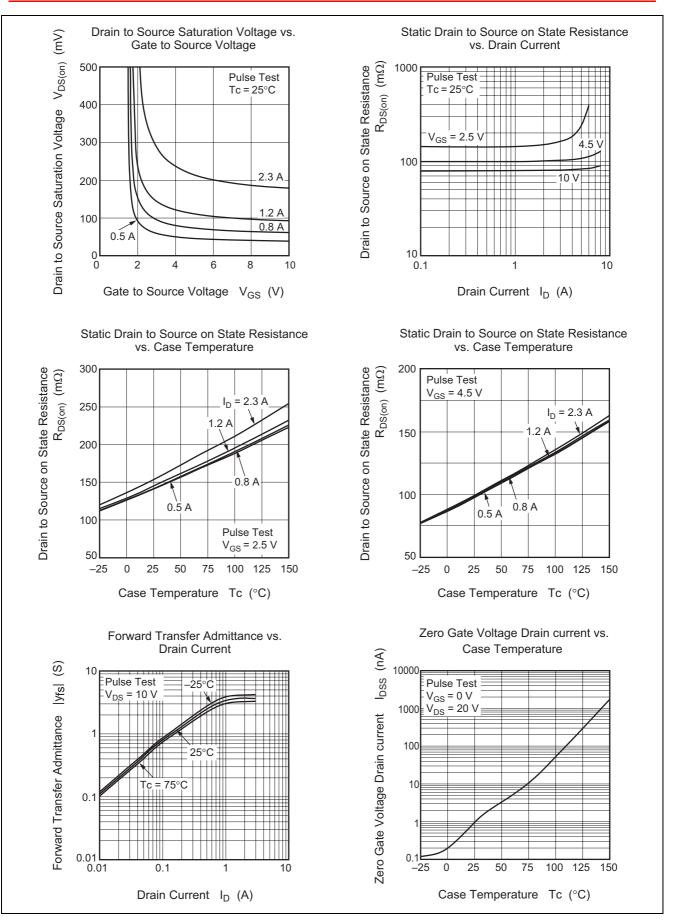
Notes: 3. Pulse test



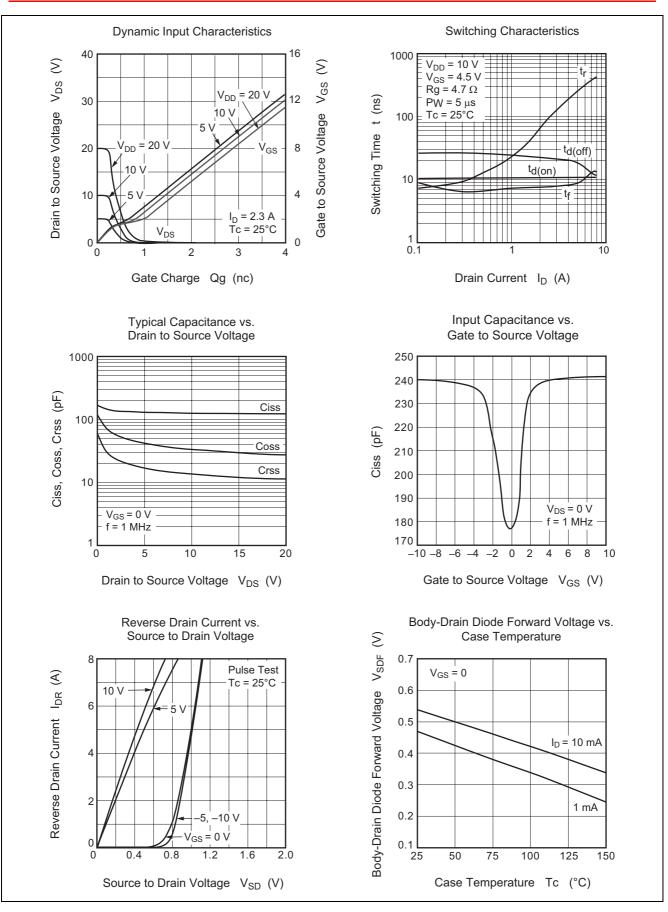
Main Characteristics





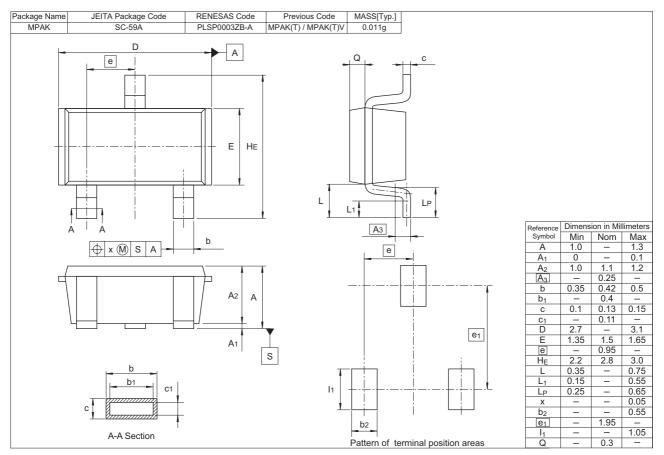








Package Dimensions



Ordering Information

Part Name	Quantity	Shipping Container
RQK0204TGDQATL-E	3000 pcs.	φ178 mm reel, 8 mm Emboss taping



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